



PATENT / DOCKET NO.: 24061.59 / TSMC2003-0121
CUSTOMER NO.: 42717

INVENTOR'S DECLARATION FOR PATENT APPLICATION

As below named inventors, we hereby declare that:

Our residence, post office address and citizenship are as stated below next to our names;

We believe we are the original, first and sole joint inventors of the subject matter which is claimed and for which a patent is sought on the invention entitled

MICROELECTRONICS PACKAGE ASSEMBLY TOOL AND METHOD OF MANUFACTURE THEREWITH

the specification of which: (check one)

_____ is attached hereto.

 X was filed on April 13, 2004
under Attorney's Docket Number 24061.59 (TSMC2003-0121)
as Application Serial No. 10/822,961
and was amended on _____ (if applicable).

We hereby authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.).

We hereby state that we have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

We acknowledge the duty to disclose information which is material to the patentability of this application in accordance with 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

FULL NAME OF INVENTOR: Chao-Yuan Su

INVENTOR'S SIGNATURE: Chao-Yuan Su DATED: ✓ 5/04/04

RESIDENCE: Hsin-Chu, Taiwan, R.O.C.

POST OFFICE ADDRESS: No. 8, Li-Hsin Rd., Science-Based Industrial Park
Hsin-Chu 300-77, Taiwan, R.O.C.

CITIZENSHIP: Taiwan, R.O.C.

FULL NAME OF INVENTOR: Hsin-Hui Lee

INVENTOR'S SIGNATURE: ✓ Hsin-Hui Lee DATED: ✓ 5/04/04

RESIDENCE: Hsin-Chu, Taiwan, R.O.C.

POST OFFICE ADDRESS: No. 8, Li-Hsin Rd., Science-Based Industrial Park
Hsin-Chu 300-77, Taiwan, R.O.C.

CITIZENSHIP: Taiwan, R.O.C.

R-72167.1